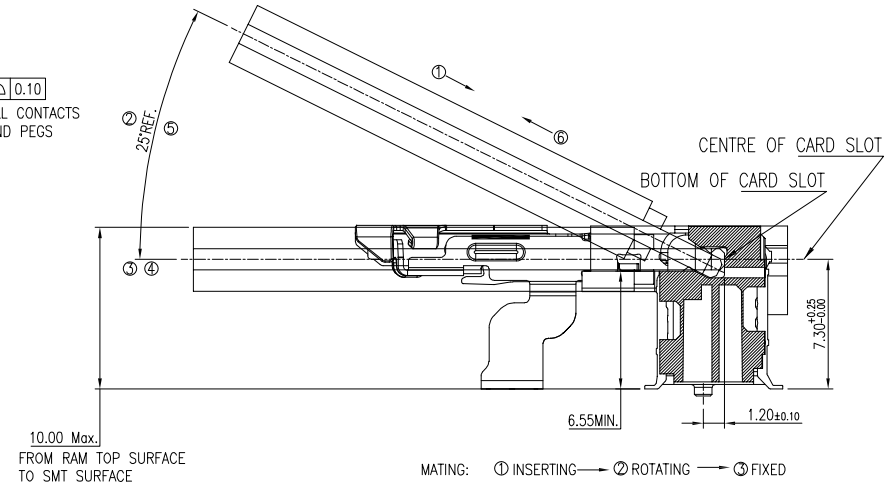
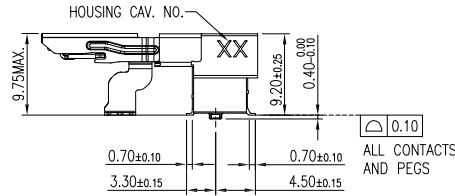
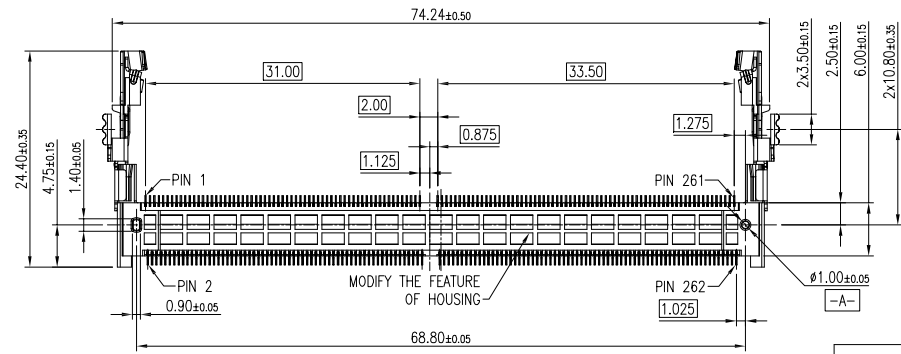
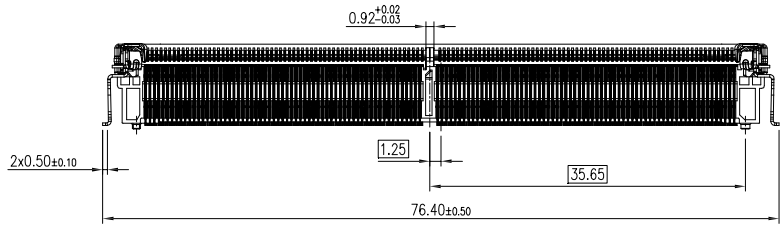
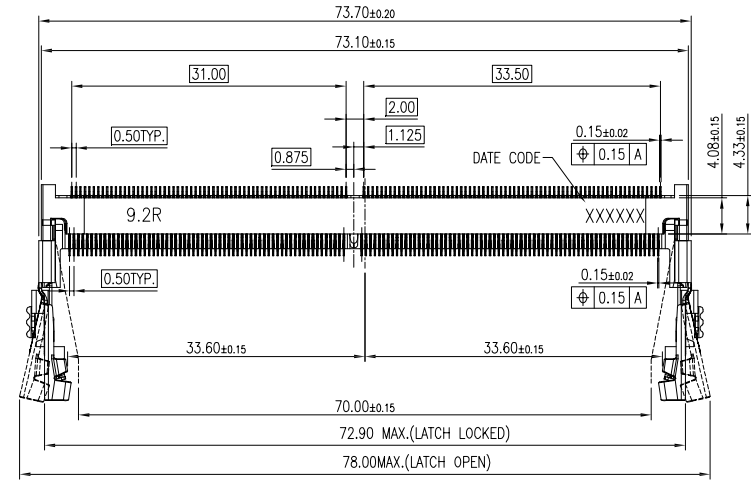




NOTES

1.MATERIAL

- 1.1HOUSING: THERMOPLASTIC.UL94V-0. COLOR:BLACK
- 1.2CONTACT:HIGH-PERFORMANCE COPPER ALLOY.
- 1.3LATCH:STAINLESS STEEL.
- 1.4PEG: STAINLESS STEEL.

2.FINISH

- 2.1CONTACT:GOLD PLATING(SEE P/N) ON CONTACT AREA AND 1~3u" GOLD PLATING ON SOLDER AREA NICKEL 50~150u"UNDER-PLATING ALL OVER
- 2.2PEG: 50~150u" TIN PLATING OVER 50~150u" NICKEL UNDER-PLATING ALL OVER

3.MSL LEVEL:MSL(MOISTURE SENSITIVITY LEVEL)=1.

4.PRODUCT NUMBER NOTE:

D5262-92 XX R R

- 52: 5.2mm HEIGHT
- CONTACT AREA PLATING
- 01: G/F
10: 10u"Au
15: 15u"Au
- PACKING OPTIONS
R: TAPE&REEL
- ORIENTATION
S: STANDARD
R: REVERSE

TOLERANCE

LINEAR ANGLES

X.±0.40 X°±

.X±0.30 .X°±

.XX±0.20 .XX°±

.XXX±0.10 .XXX°±

UMax 东莞市友贸实业有限公司
conn DONGGUAN UMAX ENTERPRISE LIMITED

APPD: Jason

MAT'L:

CHKD: Schumi

FINISH:

DRWN:Lei Songping

Q'TY:

TITLE: DDR5 SODIMM
9.2H 262PIN REVERSE TYPE.

PART NO. D5262-92XXRR

DWG NO. C-D5262-92R

UNITS SCALE SHEET REV
MM 1 : 1 1 OF 2 A

REV	ECN NO.	NAME	DATE
A	-----	FENG.PF	May.16.2024

